Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK2886

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain–source ON resistance : R_{DS} (ON) = 14 m Ω (typ.)

• High forward transfer admittance $: |Y_{fs}| = 31 \text{ S (typ.)}$

• Low leakage current : $IDSS = 100 \mu A (max) (VDS = 50 V)$

• Enhancement-mode : $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V}, I_D = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	50	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	50	V	
Gate-source voltage		V_{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	45	Α	
	Pulse (Note 1)	I _{DP}	135	Α	
Drain power dissipatio	n (Tc = 25°C)	P_{D}	40	W	
Single pulse avalanche energy (Note 2)		E _{AS}	350	mJ	
Avalanche current		I _{AR}	45	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	4	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Weight: 1.9 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.125	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 25 V, T_{ch} = 25°C (initial), L = 213 μ H, R_{G} = 25 Ω , I_{AR} = 45 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.

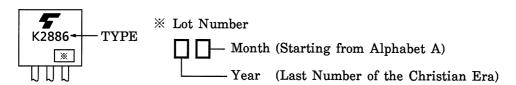
Electrical Characteristics (Ta = 25°C)

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ	
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 50 V, V _{GS} = 0 V	-	_	100	μA	
Drain-source br	eakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	50	_	_	V	
Gate threshold v	voltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	٧	
Drain-source ON resistance		R _{DS(ON)}	V _{GS} = 4 V, I _D = 25 A	1	27	36	mΩ	
		R _{DS(ON)}	V _{GS} = 10 V, I _D = 25 A	_	14	20		
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 25 A	18	31	_	S	
Input capacitano	e	C _{iss}		_	2200	_		
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	390	_	pF	
Output capacitance		Coss]		1090	_		
Switching time	Rise time	t _r	$V_{GS} = 10V$ V_{OUT} V_{OUT} V_{OUT} V_{OUT} V_{OUT} V_{OUT} V_{OUT}	_	40	_	- ns	
	Turn-on time	t _{on}		_	70	_		
	Fall time	t _f		_	130	_		
	Turn-off time	t _{off}	$V_{\mathrm{DD}} = 25 \mathrm{V}$ Duty $\leq 1\%$, $t_{\mathrm{W}} = 10 \mu\mathrm{s}$		360	_		
Total gate charge (gate-source plus gate-drain)		Q_{g}		_	66	_		
Gate-source charge		Q _{gs}	$V_{DD} \approx 40 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 45 \text{ A}$		43		nC	
Gate-drain ("miller") Charge		Q _{gd}			23			

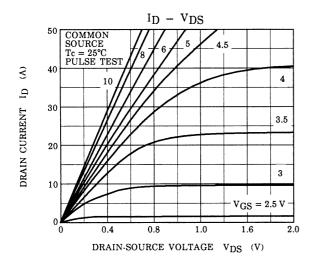
Source-Drain Ratings and Characteristics (Ta = 25°C)

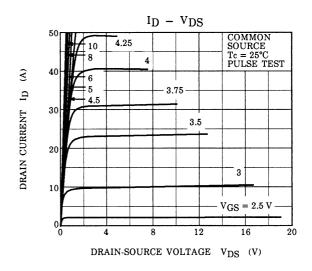
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	45	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	135	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 45 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 45 A, V _{GS} = 0 V dI _{DR} / dt = 50 A / µs		78	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 50 A / μs		90	_	μC

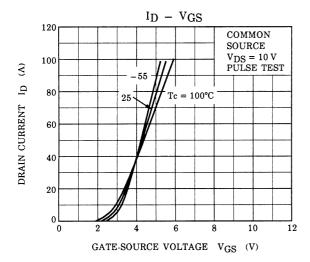
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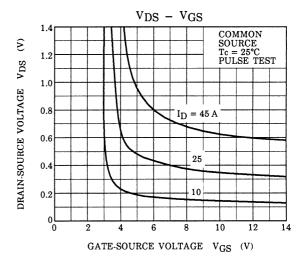


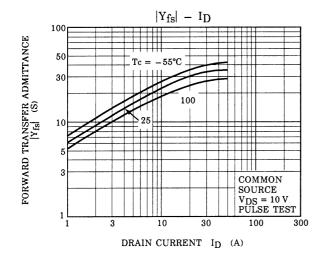
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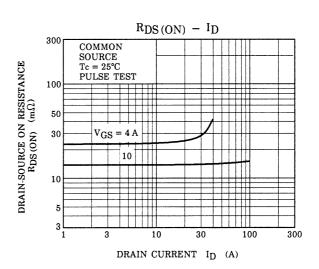


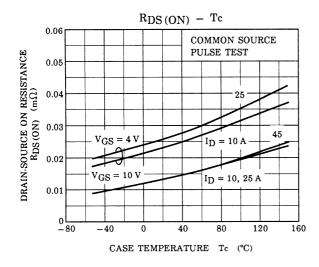


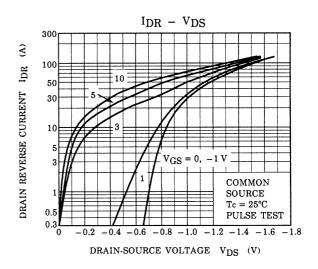


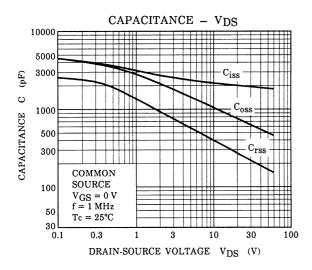


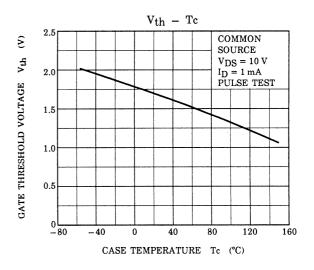


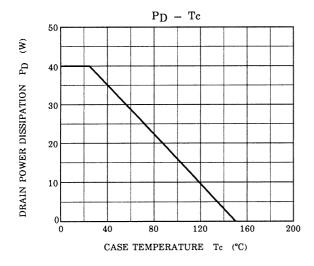


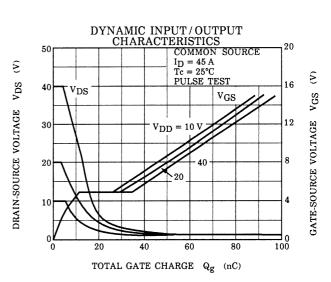




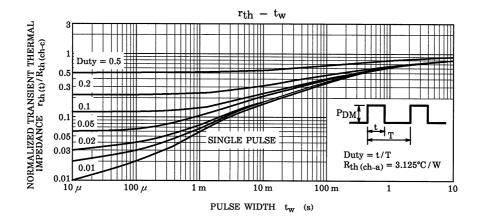


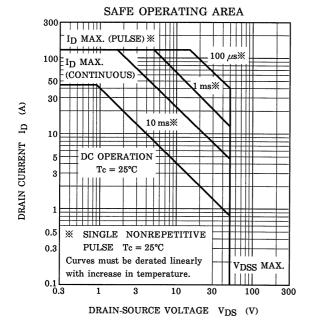


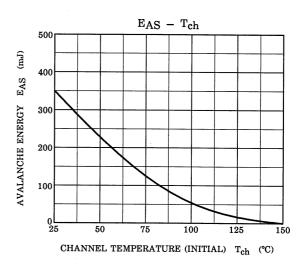


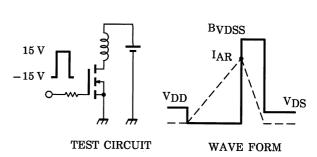


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$$\begin{aligned} &RG = 25~\Omega \\ &V_{DD} = 25~V,~L = 213~\mu H \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right) \end{aligned}$$

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